

Title (en)  
SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

Title (de)  
HALBLEITERBAUELEMENT UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)  
DISPOSITIF SEMI-CONDUCTEUR ET SON PROCEDE DE PRODUCTION

Publication  
**EP 1376452 A4 20050413 (EN)**

Application  
**EP 01274083 A 20011228**

Priority

- JP 0111640 W 20011228
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Abstract (en)  
[origin: EP1788512A1] On an adapter mounting portion 3a having a projecting cross section which is formed on a cap 3 of a small-sized memory card 1, a recessed portion of an adapter 2 side is fitted so that both parts are formed as an integral unit in a replaceable manner. Accordingly, the small-sized memory card 1 can maintain the dimensional compatibility with respect to existing memory cards whereby the small-sized memory card 1 can be used also in equipment which is designed to cope with the existing memory cards.

IPC 1-7  
**G06K 17/00**; **G06K 19/00**; **G06K 19/077**

IPC 8 full level  
**G06K 19/077** (2006.01); **G11C 5/00** (2006.01); **H01L 23/02** (2006.01); **H05K 5/02** (2006.01); **H05K 7/02** (2006.01); **H05K 7/06** (2006.01); **H05K 7/08** (2006.01); **H05K 7/10** (2006.01); **H05K 7/12** (2006.01)

CPC (source: EP KR US)  
**G06K 19/07** (2013.01 - KR); **G06K 19/077** (2013.01 - EP US); **G06K 19/07732** (2013.01 - EP US); **G06K 19/07737** (2013.01 - EP US); **G06K 19/07739** (2013.01 - EP US); **G06K 19/07743** (2013.01 - EP US); **G11C 5/04** (2013.01 - EP US); **H01L 23/5388** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 25/18** (2013.01 - EP US); **H05K 5/026** (2013.01 - EP US); **H05K 5/0282** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05554** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/85399** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01039** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/10161** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

C-Set (source: EP US)  
1. **H01L 2224/45144 + H01L 2924/00014**  
2. **H01L 2224/85399 + H01L 2924/00014**  
3. **H01L 2224/05599 + H01L 2924/00014**  
4. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**  
5. **H01L 2924/181 + H01L 2924/00012**

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**US 26778402 A 20021010**; AT 01274083 T 20011228; CN 01808343 A 20011228; CN 200610081869 A 20011228; CN 200610081870 A 20011228; CN 200610081871 A 20011228; CN 200610081872 A 20011228; DE 60128151 T 20011228; EP 01274083 A 20011228; EP 07003853 A 20011228; JP 0111640 W 20011228; JP 2002580253 A 20011228; JP 2009036042 A 20090219;

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